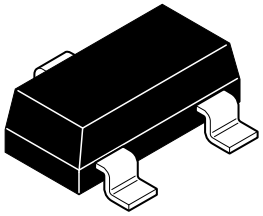
ZXTP23015CFH
15V, SOT23, PNP medium power transistor

Summary



$V_{(BR)CES}$ > -15V, $V_{(BR)CEO}$ > -15V

$V_{(BR)ECO}$ > -6V

$I_{C(CONT)}$ = -6A

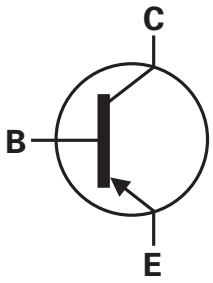
$R_{CE(SAT)}$ = 20mΩ typical

$V_{CE(SAT)}$ < -36mV @ -1A

P_D = 1.25W

Complementary part number ZXTN23015CFH

Description



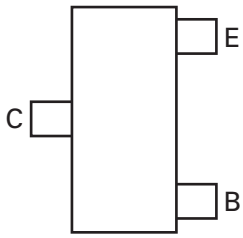
Advanced process capability and package design have been used to maximize the power handling and performance of this small outline transistor. The compact size and ratings of this device make it ideally suited to applications where space is at a premium.

Feature

- Higher power dissipation SOT23 package
- High peak current
- Low saturation voltage
- 15V forward blocking voltage
- 6V reverse blocking voltage

Applications

- High side disconnect switches
- DC - DC converters
- MOSFET and IGBT gate driving
- Motor drive
- Relay, lamp, and solenoid drive



Pinout - top view

Ordering information

Device	Reel size (inches)	Tape width	Quantity per reel
ZXTP23015CFHTA	7	8mm	3000

Device marking

317

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Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Collector-base voltage	V_{CBO}	-15	V
Collector-emitter voltage	$V_{(BR)CES}$	-15	V
Collector-emitter voltage	V_{CEO}	-15	V
Emitter-base voltage	V_{EBO}	-7.0	V
Emitter-collector voltage	V_{ECO}	-6.0	V
Peak pulse current	I_{CM}	-10	A
Continuous collector current (c)	I_C	-5	A
Continuous collector current (d)	I_C	-6	A
Base current	I_B	-1.2	A
Power dissipation @ T_A=25°C (a) Linear derating factor (a)	P_D	0.73 5.84	W mW/°C
Power dissipation @ T_A=25°C (b) Linear derating factor (b)	P_D	1.05 8.4	W mW/°C
Power dissipation @ T_A=25°C (c) Linear derating factor (c)	P_D	1.25 9.6	W mW/°C
Power dissipation @ T_A=25°C (d) Linear derating factor (d)	P_D	1.81 14.5	W mW/°C
Operating and storage temperature	T_j:T_{stg}	-55 to +150	°C

Thermal resistance

Parameter	Symbol	Value	Unit
Junction to ambient (a)	$R\Theta_{JA}$	171	°C/W
Junction to ambient (b)	$R\Theta_{JA}$	119	°C/W
Junction to ambient (c)	$R\Theta_{JA}$	100	°C/W
Junction to ambient (d)	$R\Theta_{JA}$	69	°C/W

NOTES:

(a) For a device surface mounted on 15mm x 15mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

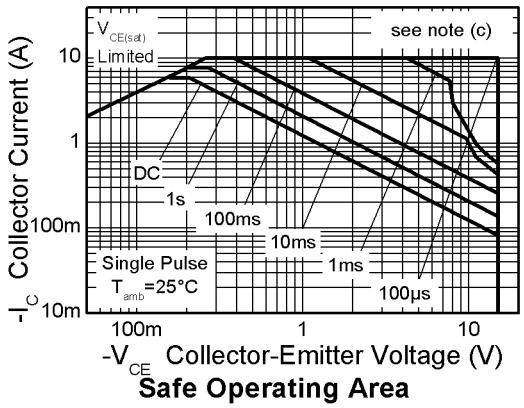
(b) Mounted on 25mm x 25mm x 1.6mm FR4 PCB with a high coverage of single sided 2 oz copper in still air conditions.

(c) Mounted on 50mm x 50mm x 1.6mm FR4 PCB with a high coverage of single sided 2 oz copper in still air conditions.

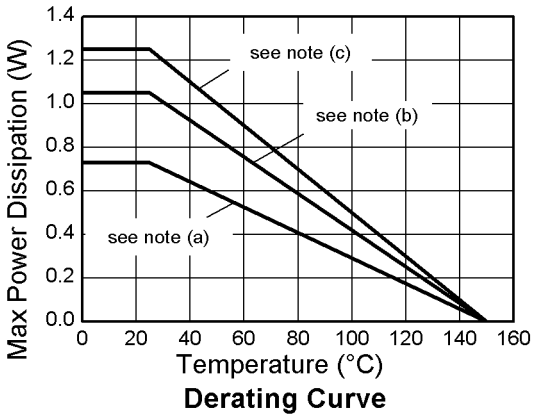
(d) As (c) above measured at t<5secs.

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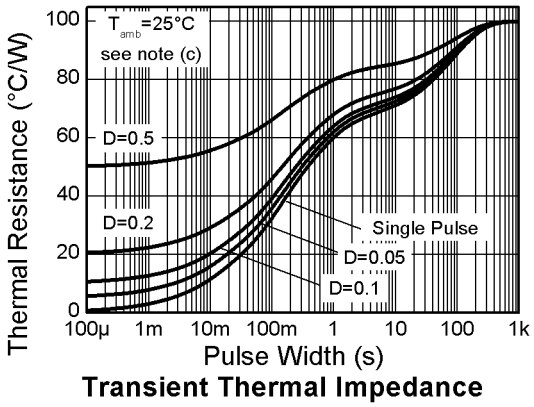
Characteristics



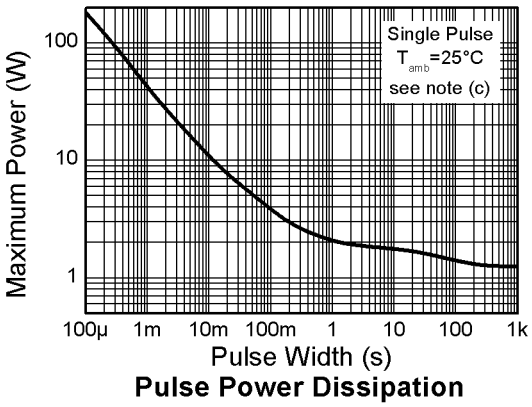
Safe Operating Area



Derating Curve



Transient Thermal Impedance



Pulse Power Dissipation

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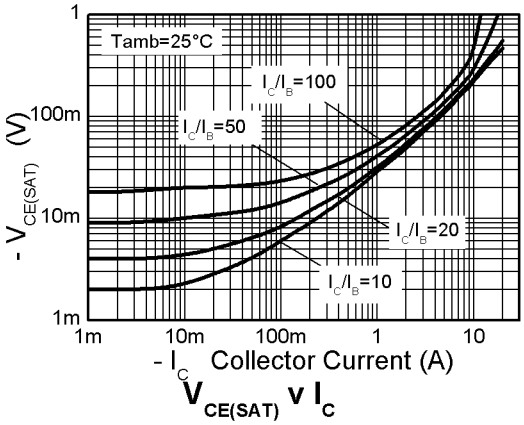
ELECTRICAL CHARACTERISTICS (at T_{AMB} = 25°C unless otherwise stated)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-base breakdown voltage	$V_{(BR)CBO}$	-15	-40		V	I_C=-100μA
Collector-emitter breakdown voltage	$V_{(BR)CES}$	-15	-40		V	I_C =-100μA
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	-15	-25		V	I_C=-10mA(*)
Emitter-base breakdown voltage	$V_{(BR)EBO}$	-7.0	-8.2		V	I_E=-100μA
Emitter-collector breakdown voltage	$V_{(BR)ECO}$	-6.0	-8.5		V	I_E=-100μA
Collector-emitter cut-off current	I_{CES}			-20	nA	V_{CE}=-12V
Collector-base cut-off current	I_{CBO}			-20	nA	V_{CB}=-12V
Emitter-base cut-off current	I_{EBO}			-10	nA	V_{EB}=-6V
Static forward current transfer ratio	H_{FE}	200	380			I_C=-10mA, V_{CE}=-2V (*)
		200	350	560		I_C=-500mA, V_{CE}=-2V
		140	220			Ic=-6A, V_{CE}=-2V
Collector-emitter saturation voltage	$V_{CE(sat)}$		-6	-10	mV	I_C=-100mA, I_B=-10mA(*)
			-27	-36	mV	I_C=-1A, I_B=-100mA(*)
			-90	-120	mV	I_C=-3A, I_B=-60mA(*)
			-140	-190	mV	I_C=-6A, I_B=-240mA(*)
Base-emitter saturation voltage	$V_{BE(sat)}$		-0.83	-0.93	V	I_C=-3A, I_B=-60mA(*)
			-0.93	-1.03	V	I_C=-6A, I_B=-240mA(*)
Base-emitter turn-on voltage	$V_{BE(on)}$		-0.83	-0.93	V	I_C=-6A, V_{CE}=-2V(*)
Transition frequency	f_T		270		MHz	Ic=-500mA, V_{CE}=-2V, f=50MHz
Output capacitance	C_{obo}		78.4		pF	V_{CB}=-10V, f=1MHz
Delay time	$t_{(d)}$		16		ns	V_{CC}=-5V, I_C=-3A, I_{B1}=I_{B2}=-150mA
Rise time	$t_{(r)}$		13		ns	
Storage time	$t_{(stg)}$		123		ns	
Fall time	$t_{(f)}$		9		ns	

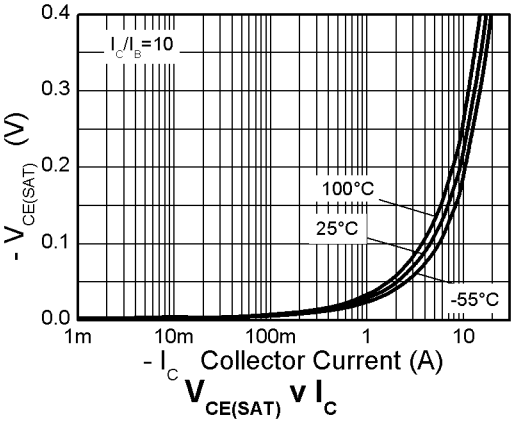
NOTES:
(*) Measured under pulsed conditions. Pulse width = 300μS. Duty cycle ≤2%.

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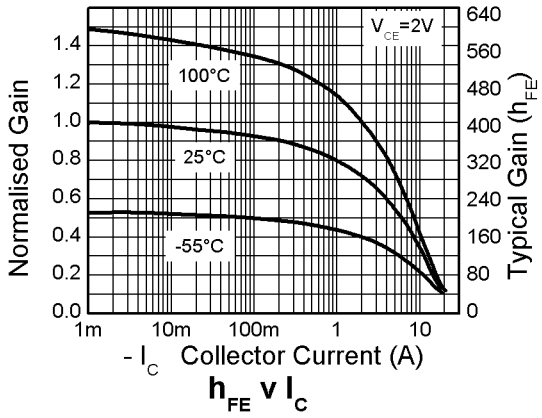
Typical characteristics



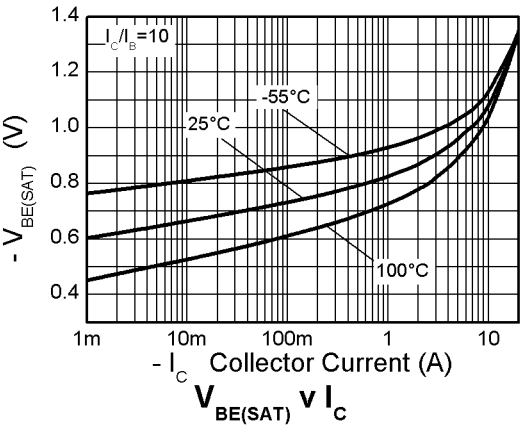
$V_{CE(SAT)}$ v I_C



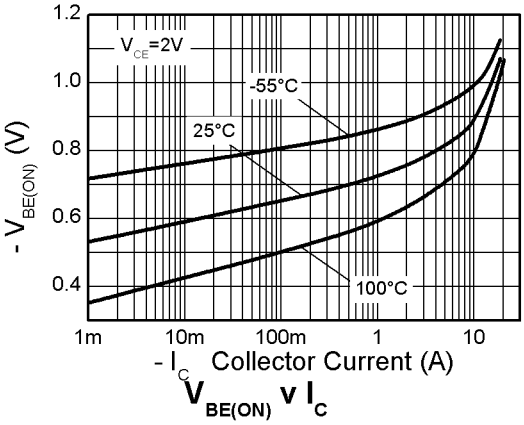
$V_{CE(SAT)}$ v I_C



h_{FE} v I_C



$V_{BE(SAT)}$ v I_C



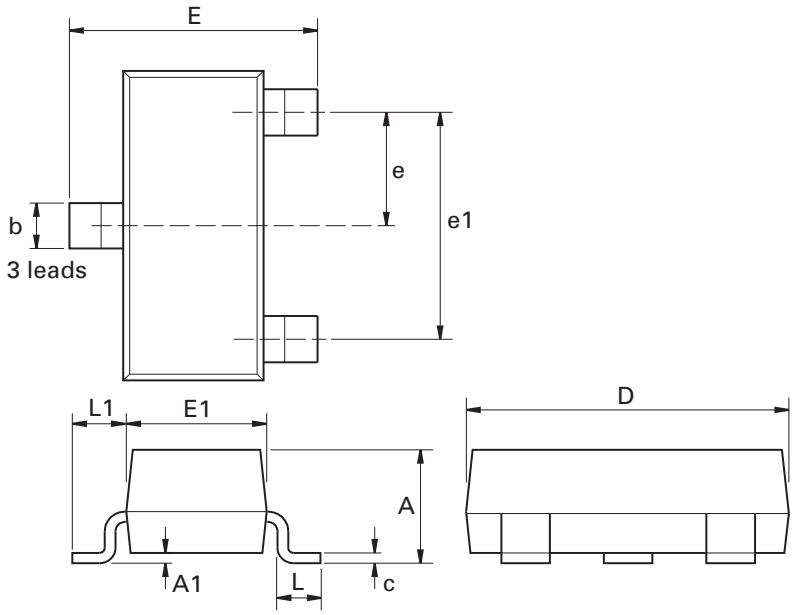
$V_{BE(ON)}$ v I_C

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Package outline - SOT23



Dim.	Millimeters		Inches		Dim.	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	-	1.12	-	0.044	e1	1.90 NOM		0.075 NOM	
A1	0.01	0.10	0.0004	0.004	E	2.10	2.64	0.083	0.104
b	0.30	0.50	0.012	0.020	E1	1.20	1.40	0.047	0.055
c	0.085	0.20	0.003	0.008	L	0.25	0.60	0.0098	0.0236
D	2.80	3.04	0.110	0.120	L1	0.45	0.62	0.018	0.024
e	0.95 NOM		0.037 NOM		-	-	-	-	-

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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